



# EEE112 REVIEW SESSION

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May 16<sup>th</sup> 2024



# Final Exam Structure

Duration: **2 hours**

Type: Closed Book Exam

**Final Exam = Section A + Section B**

**Section A (40%):** 20 MCQs (2% each)

For each question, **select just ONE of the four possible answers**, and **write its letter (a), (b), (c) or (d) on the answer booklet(s)**.

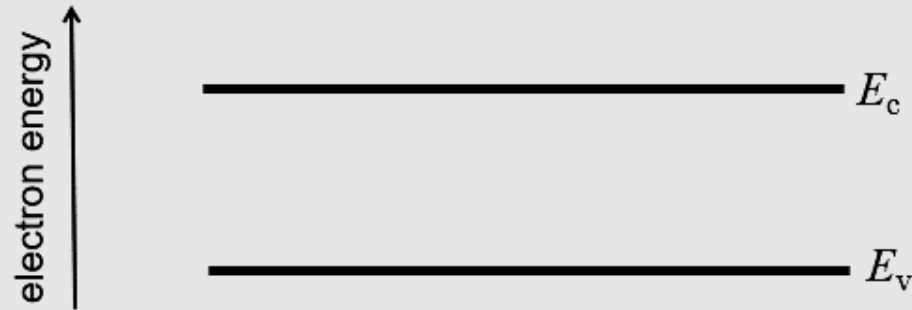
**Section B (60%):** 3 questions

Answer should be written on the **same answer booklet(s)** provided and submitted after the exam.

# Section A (40%)

## Example 1

**CT2.** Which one is correct?



- (A)
- $E_v$  is bottom edge of the conduction band
  - $E_c$  is top edge of the valence band
  - $E_c$  and  $E_v$  are separated by the **band gap energy**  $E_g$
- (B)
- $E_c$  is bottom edge of the conduction **level**
  - $E_v$  is top edge of the valence **level**
  - $E_c$  and  $E_v$  are separated by the **level gap energy**  $E_g$
- (C)
- $E_c$  is bottom edge of the conduction **band**
  - $E_v$  is top edge of the valence **band**
  - $E_c$  and  $E_v$  are separated by the **band gap energy**  $E_g$

# Section A (40%)

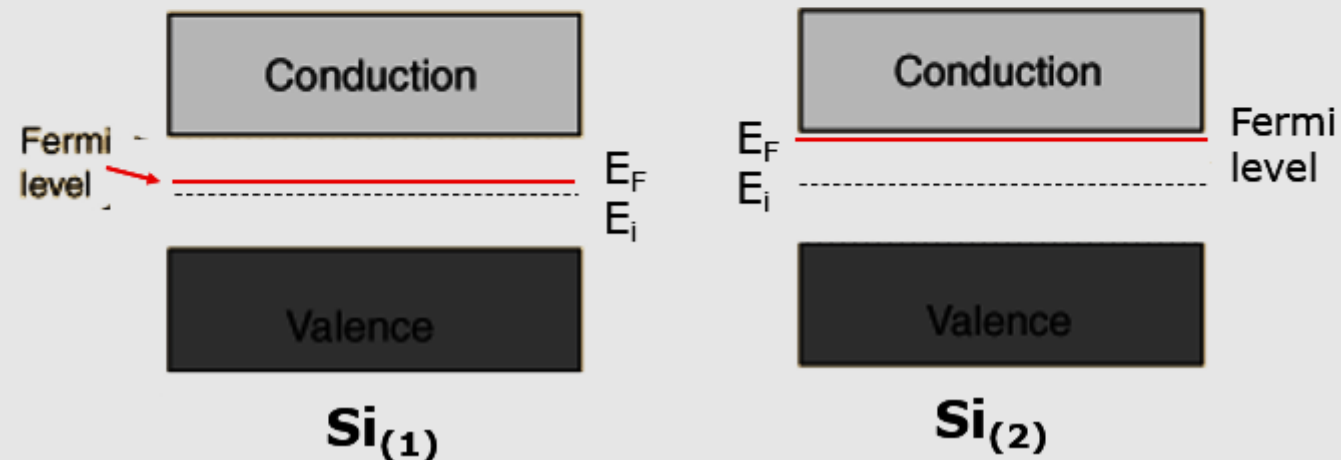
**CT4**

**Example 2**

**Energy band diagrams of two silicon materials,  $\text{Si}_{(1)}$  and  $\text{Si}_{(2)}$ , are shown below and  $(E_F - E_V)_{(1)} < (E_F - E_V)_{(2)}$ .**

**Which one is true, compared with  $\text{Si}_{(2)}$ ?**

- (A)  $\text{Si}_{(1)}$  is a stronger p-type. (B)  $\text{Si}_{(1)}$  is a weaker p-type.  
(C)  $\text{Si}_{(1)}$  is a weaker n-type. (D)  $\text{Si}_{(1)}$  is a stronger n-type.

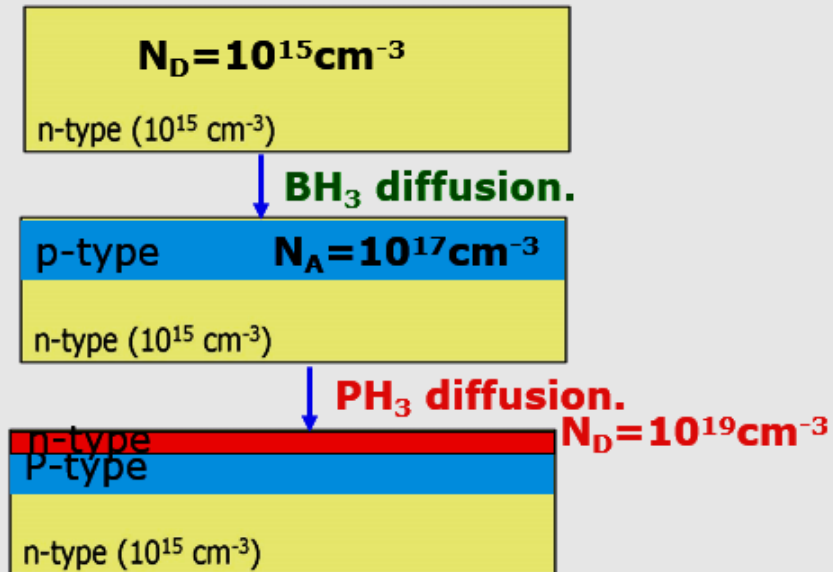


# Section A (40%)

## Example 3

**CT12.** Fig. shows a formation of npn transistor. After  $\text{PH}_3$  diffusion, the **hole** density of the **top** layer is

- (A)  $10^{19}\text{cm}^{-3}$ . (B)  $10^{18}\text{cm}^{-3}$ . (C)  $10^{17}\text{cm}^{-3}$ .  
(D)  $10^3\text{cm}^{-3}$ . (E)  $10^1\text{cm}^{-3}$ .



# Section B (60%)

## Example 1

### B1

Consider an intrinsic silicon (Si) sample at room temperature 300 K (i.e. 27 °C) in equilibrium condition.

- (a). If the working condition of the Si sample changes to that with an operation temperature of 200 °C because of overheating, determine the intrinsic carrier concentration  $n_i$  in equilibrium.  
(4 marks)
- (b). If the intrinsic Si sample is doped with boron (B), what are the majority and minority carriers?  
(2 marks)
- (c). If the dopant concentration in (b) is  $1 \times 10^{15} \text{ cm}^{-3}$ , determine the majority and minority carrier concentrations at room temperature 300 K. Please specify which concentration is for the majority carriers and which for the minority carriers.  
(5 marks)
- (d). Draw the energy band diagram for such a Si sample doped with boron (B). Please label clearly the conduction band edge  $E_c$ , the valence band edge  $E_v$  and the Fermi energy levels (including the intrinsic one  $E_i$ ).  
(6 marks)
- (e) If the doped Si sample works at 200 °C because of an overheating condition, calculate the minority carrier concentration in equilibrium.  
(3 marks)

## Section B (60%)

### Example 2

An inverter with a resistor load,  $R_L$ , is shown in Figure B, calculate the aspect ratio  $W/L$ , of the driver  $T_D$ , with the following specification:

- i) the threshold voltage of the driver is  $V_T = 1\text{ V}$ ,
- ii) the device constant  $\beta_0 = \mu_n C_{ox} = 12.5 \times 10^{-4}\text{ AV}^{-2}$ ,
- iii)  $R_L = 1\text{ k}\Omega$ ,
- iv)  $V_{DD} = 5\text{ V}$ .

(25 marks)

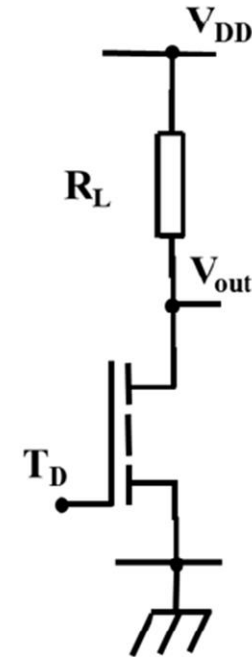


Figure B: Inverter with resistive load

# Key-points of the module

- Capacitance vs. gate voltage characteristic of a MOS capacitor with n-type and p-type silicon substrate
- Energy-bands through an MOS capacitor
- $I_D$ - $V_{GS}$  curve and  $I_D$ - $V_{DS}$  curve of an nMOSFET
- Drain current of nMOSFET
- Energy band diagrams of silicon materials
- Miller indices and yields
- Fermi energy level and Fermi function
- Diffusion constant and mobility
- Generation and recombination
- Doping element, materials and counter doping
- Hole concentration and electron concentration
- IC Technology: deposition, photolithography, doping, CVD, PVD



# Key-points of the module

- **Semiconductor Fundamentals II**

- Intrinsic semiconductor
- Doping, majority free carriers, doping concentration

- **MOS Capacitor**

- Capacitor structure
- Energy band diagram
- Effects of applied bias
- Biasing conditions for p-type Si
- Biasing conditions for n-type Si
- High frequency or low frequency
- Block charge density diagrams

- **Technology**

- Photolithography
- Mask, process step
- Positive and negative photoresists

# Extra Support

- **Key-points of the module**
- **MCQ Example Part 1** and **2** on Learning Mall
- **Extra Q&A Session** (not Compulsory, **in the reading week**)
  - Will announce in the learning Mall later
  - Please come to my office **SC342**







TIME TO SAY GOODBYE!  
祝君好运、江湖再见！

Gary, Chun Zhao, PhD  
May 16<sup>th</sup> 2024